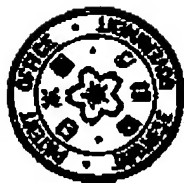


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CORP

(72) Inventor: FUJII HIROYUKI

(74) Representative:

(54) MANUFACTURE OF
RESIN-MOLD
SEMICONDUCTOR DEVICE
AND SEALING DEVICE
USED THEREFOR

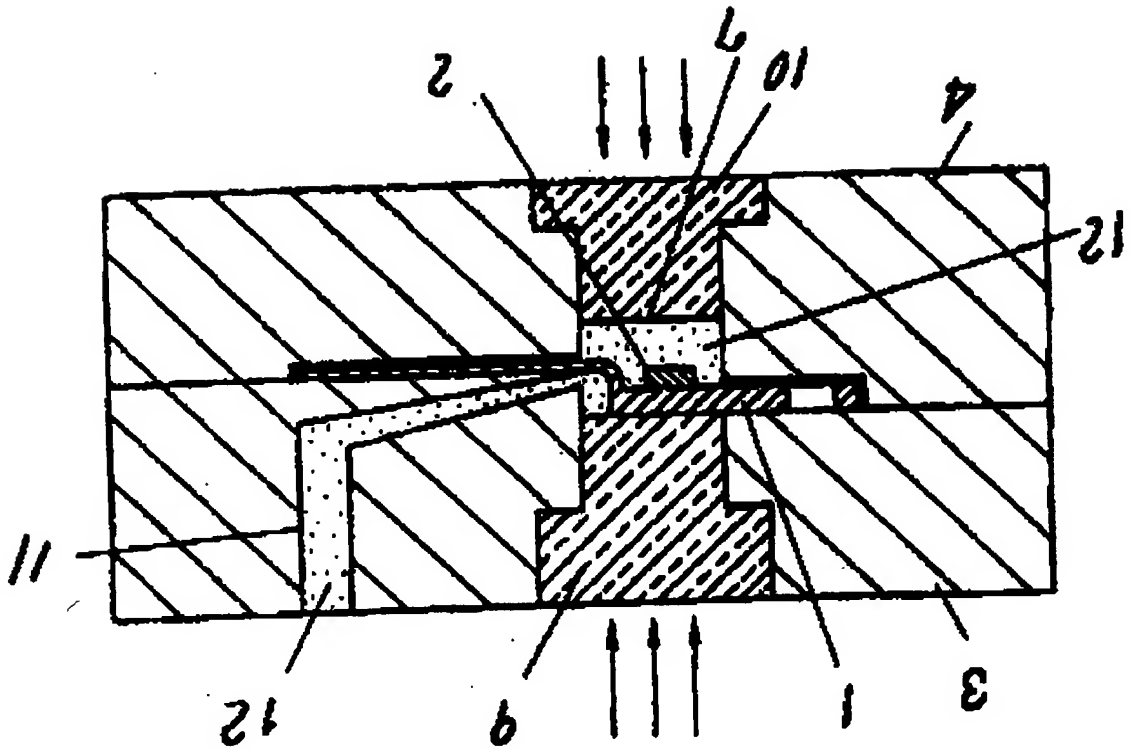
(57) Abstract:

PURPOSE: To contrive the reduction of the cost of resin sealing by using molding resin of ultraviolet-curing type for sealing resin so as to selectively cure only the molding resin of ultraviolet-curing type to be poured in the cavity.

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CONSTITUTION: The built-up body of a transistor in which a transistor element 2 is bonded to a substrate supporting part 1 of the lead frame and further connection by metal thin wires has been completed is arranged between the upper and lower molding dies 3 and 4. Next, the ultraviolet-curing resin 13 is poured into the cavity 7 through a molding resin supply hole 11. After that, the sealing molds are irradiated with the ultraviolet rays as indicated by the arrows. As the resin layers 9 and 10 of the molding dies 3 and 4 consist of the resin of ultraviolet-transparent type, the ultraviolet rays penetrates through said layers 9 and 10 to reach the cavity 7. Accordingly, only the resin poured in the cavity 7 is subjected to curing reaction and is cured. In this manufacturing method, there is no waste of molding resin, and heating of the resin and of the sealing molds is unnecessary so that improvement of operation efficiency and reduction of the cost of resin sealing can be contrived.

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